

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

1-12. (Canceled)

13. (Previously presented) A method of EMI shielding a circuit board or flexible circuitry, the method comprising:
encapsulating at least one electronic component with a conforming insulating base coating;
vacuum metallizing a first conductive layer over the insulating base coating; and
grounding the first conductive layer to a ground trace to provide a grounded EMI shield for the electronic component.

14. (Canceled)

15. (Previously presented) The method of claim 13 further comprising maintaining a temperature of the electronic component and insulating base coating below approximately 200°C during vacuum metallizing.

16. (Original) The method of claim 13 wherein the first conductive layer comprises aluminum, copper, silver, gold, tin, or nickel-chromium.

17. (Original) The method of claim 13 further comprising applying a second conductive layer over the first conductive layer

18. (Original) The method of claim 13 further comprising applying an insulating conformal layer over the first conductive layer.

19. (Original) The method of claim 18 wherein the conformal layer is waterproof.

20. (Previously presented) The method of claim 13 further comprising improving the adhesion between the conforming insulating base coating and the first conductive layer by using a glow discharge process.

21. (Original) The method of claim 13 further comprising positioning the ground trace around a periphery of the component.

22. (Previously presented) The method of claim 13 wherein the at least one electronic component comprises a first and second component, wherein the ground trace is disposed between the first and second component.

23. (Original) The method of claim 13 further comprising exposing the ground trace through the insulating coating.

24-58. (Canceled)

59. (Currently amended) A method of shielding an electronic component on a printed circuit board, the method comprising:

attaching a base portion of a metallized ~~dielectric~~ substrate shield body onto a top surface of a ground trace that is disposed on the printed circuit board, wherein the base portion ~~comprises a flange that~~ contacts the top surface of the ground trace and extends substantially parallel to the ~~surface of the printed circuit board~~ top surface of the ground trace and a plurality of walls that extend substantially orthogonal to ~~a surface of the printed circuit board~~ the top surface of the ground trace, the ground trace surrounding the electronic component; and

removably coupling a top portion of a metallized ~~dielectric~~ substrate shield body to the plurality of walls of the base portion of the metallized ~~dielectric~~ substrate shield body to enclose the electronic component.

60. (Currently amended) The method of claim 59 further comprising positioning a conductive adhesive over at least a portion of a the top surface of the ground trace prior to attaching the base portion of the metallized substrate shield body to the ground trace.

61. (Previously presented) The method of claim 59, wherein removably coupling comprises overlapping a portion of the top portion over the plurality of walls of the base portion of the metallized substrate shield body.

62. (Canceled)

63. (Previously presented) The method of claim 59 further comprising positioning protrusions between a periphery of the top portion of the metallized substrate shield body and the base portion of the metallized substrate shield body.

64. (Original) The method of claim 63 wherein the protrusions are spaced no larger than one-half a wavelength of electromagnetic radiation emitted from the electronic component.

65. (Previously presented) The method of claim 59 wherein removably coupling comprises inserting a tab in a groove, wherein one of the tab and groove is disposed on the top portion of the metallized substrate shield body and the other of the tab and groove is disposed on the base portion of the metallized substrate shield body.

66. (Canceled)

67. (Currently amended) The method of claim 59 wherein the metallized dielectric substrate shield body comprises one of a thermoform and injection molded plastic.

68-72. (Canceled)